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Electronic Components Industry Association (ECIA)
1111 Alderman Drive, Suite 400
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Phone: (678) 393-9990
Fax: (678) 393-9998

rwillis@eciaonline.org

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TABLE OF CONTENTS

Alloy and Core-Shell Silver/Palladium Platelets for Ultra-Low Fire MLCC's	1
<i>Brendan Farrell, Daniel Andreescu, Dan V. Goia</i>	
Conductive and Electroactive Polyanilines with Unique Tunable Work Functions	10
<i>Patrick J. Kinlen, Yevgenia V. Ulyanova, Gary D. Rawlings</i>	
Suppression of Low-Frequency Dispersion in TiO₂ Sintered Capacitor by Doping Ti Metal	16
<i>Kagata Abe, Yutaka Abe</i>	
Removal of Contaminants into Formation Tank with Ion Exchange Resins.....	23
<i>Pablo A. Ruiz Flores, Miguel E. Esquivel Aguirre, Juan C. Perez, Juan J. Torres</i>	
Low-Permitivity and High-Q Ceramics, 2MgO-SintenSeki, at Microwave Frequency Region	34
<i>Yutaka Abe, Makoto Kagata, Haruo Morimoto</i>	
Evaluation of Improved CVD Nickel Powders for Thin Electrode MLCC	38
<i>Takehiko Yamagata, Hiroshi Yamane</i>	
Development of Second Generation, Pb Free, Ultra Low Fire (< 1000C), High Voltage, X7(8)R	45
Dielectric Formulations.....	45
<i>Walt Symes, Mike Chu, Everette Davis, Joseph Capurso</i>	
Design Trends and New Challenges for Advanced Implantable Medical Devices	53
<i>Bob Stevenson</i>	
Dielectric Aluminum Oxides: Nano-Structural Features and Composites	54
<i>J.L. Stevens, A.C. Geiculescu, T.F. Strange</i>	
The Effect of Fiber Thickness and Thickness Uniformity on CV/g Behavior of Ta Ribbon Type Fibers.....	68
<i>William T. Nachtrab, Terence Wong, James Wong, Terrance Tripp</i>	
Facedown Terminations Improve Ripple Current Capability.....	79
<i>John Prymak, Peter Blais, Bill Long</i>	
Metallized Polypropylene Film Energy Storage Capacitors For Low Pulse Duty	87
<i>Ralph M. Kerrigan</i>	
I, Robot – A Method for Flexible, Consistent Manufacturing of Capacitors.....	95
<i>Daniel Johnson, John Sturmer</i>	
Reliability and Critical Applications of Tantalum Capacitors	100
<i>Yuri Freeman, Randy Hahn, Philip Lessner, John Prymak</i>	
Flexure Robust Capacitors	111
<i>Bill Sloka, Dan Skamser, Reggie Phillips, Allen Hill, Mark Laps, Roy Grace, John Prymak, Michael Randall, Aziz Tajuddin</i>	
High Energy Density Polymer Dielectrics for Capacitor Applications	127
<i>Shihai Zhang, Baojin Chu, Xin Zhou, Bret Neese, Qiming Zhang</i>	
Polycarbonate Capacitors Yesterday, Today and Tomorrow.....	137
<i>Sal Cesario</i>	
Ripple Current and Electrical Noise Characterization of DC BUS Capacitors for Future Power Electronics	144
<i>Teppei Akiyoshi, Guanghui Wang, Heath Hofmann, Mike Lanagan</i>	
New Low Profile Low ESL Tantalum Multi-anode Capacitor Concept Brings Better Cost versus Performance Value	157
<i>T. Zedniecek, L. Marek, S. Zedniecek</i>	
High CV BME C0G	163
<i>Xilin Xu, Pascal Pinceloup, Abhijit Gurav, Michael Randall, Aziz Tajuddin</i>	
Precision Laser Trimmable Passives	173
<i>Kevin D. Christian</i>	
The Effect of Silver Polymer Termination on the Equivalent Series Resistance of High Voltage Ceramic Capacitors	177
<i>Omar Al Taher, Chris England</i>	
Capacitors for Reduced Microphonics and Sound Emission	189
<i>Mark Laps, Roy Grace, Bill Sloka, John Prymak, Xilin Xu, Pascal Pinceloup, Abhijit Gurav, Michael Randall, Philip Lessner, Aziz Tajuddin</i>	
Decoupling Solutions	198
<i>Michael Randall, Bill Sloka, Mark Laps, Garry Renner, John Prymak, Peter Blais, Aziz Tajuddin</i>	
Thin Film RCL Filters.....	214
<i>Kevin D. Christian</i>	

Aluminum Capacitor Anode Foils for Miniaturized Applications	219
<i>H. A. Post, G. Tempelman, M. van Zijtveld</i>	
Tantalum Capacitors Bring Micro-Miniaturisation to Electronic Devices.....	225
<i>W. Millman, D. Huntingdon</i>	
MLCC ESD Characterization	236
<i>Ron Demcko, Brian Ward</i>	
Impact of Pad Design and Spacing on AC Breakdown Performance.....	242
<i>John Maxwell, Enrique Lemus</i>	
Tantalum Chip for Mission Critical Applications – The Development of Established Reliability	
Versions of Low ESR and Failsafe Technologies	248
<i>Chris Reynolds, Brian Brunette</i>	
Effect of Temperature Cycling and Exposure to Extreme Temperatures on Reliability of Solid Tantalum Capacitors.....	256
<i>Alexander Teverovsky</i>	
Infrared Flash Thermographic Location of a Short in a Solid Tantalum Capacitor.....	284
<i>Norman Helmold</i>	
Hysteresis Measurements of Multi-Layer Ceramic Capacitors Using a Sawyer-Tower Circuit	285
<i>Larry E. Mosley, Jason S. Schrader</i>	
Thick Film Resistors Testing by Electro-Ultrasonic Spectroscopy.....	296
<i>V. Sedlakova, J. Sikula</i>	
Voltage Breakdown Mechanisms in High Voltage Rated, Surface Mount MLCCs.....	304
<i>J. Bultitude, P. Gormally, J. Rogers, J. Jiang</i>	
Niobium Oxide and Tantalum Capacitors: Leakage Current and M-I-S Model Parameters.....	311
<i>J. Sikula, V. Sedlakova, H. Navarova, J. Hlavka, M. Tacano, Z. Sita</i>	
Low Impedance Ta Capacitors to Serve the Needs of the Electronics Industry.....	320
<i>Randy Hahn, Jonathan Paulsen</i>	
Determining Ripple Current Capability in Tantalum Hybrid Capacitors	332
<i>David Evans</i>	
Multilayer Aluminum Oxynitride Capacitors for Higher Energy Density, Wide Temperature Applications.....	342
<i>Kevin R. Bray, Richard L.C. Wu, Sandra Fries-Carr, Joseph Weimer</i>	
New RF Passive Discrete and Integrated Technologies Combining Ultra-Stable Performance and Smallest Size.....	351
<i>Chris Reynolds</i>	
Addressing Tantalum Capacitor Technology Challenges	362
<i>Alex Eidelman</i>	
Thin Film MLCC.....	372
<i>Michael Randall, Dan Skamser, Tony Kinard, Javaid Qazi, Aziz Tajuddin, Susan Trolier-McKinstry, Clive Randall, Song Won Ko, Tanawadee Dechakupt</i>	
Author Index	